

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L21	506185	STI or isolation or LOCOS or (Buried adj oxide) or ((trench or groove) same (oxide or SiO <sub>2</sub> or SiO <sub>2</sub> or dielectric or insulat\$6))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:56
L22	49632	21 same (void or defect\$6 or airgap or air or space or pore)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:57
L23	9437	22 same (test\$6 or detect\$6 or sens\$6 or determin\$6 or measur\$6 or monitor\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:59
L24	7028	23 and (gate or wordline or line)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 15:59
L25	3890	23 and ((gate or wordline or line) same (voltage or current or electric\$6 or potential))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 16:00
L26	1535	25 and ((semiconductor or silicon) near20 (wafer or substrate))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 16:01
L27	750	26 and ((test or active) near20 (region or area or structure))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 16:02
L28	709	27 and (@ad<"20031118" or @rlad<"20031118")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 16:03

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	1484	(STI or (trench adj isolation)) same (void or air or airgap or gap)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 10:37
L5	106	4 and ((test\$6 or detect\$6 or measur\$6 or determin\$6) near20 (void or airgap or air or gap))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 10:38
L6	99	5 and (@ad<"20031118" or @rlad<"20031118")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 10:38

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	479	(STI or (shallow adj trench adj isolation)) same void	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 10:33
L2	238	1 and (test\$6 or detect\$6 or measur\$6 or determin\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 10:34
L3	219	2 and (@ad<="20031118" or @rlad<="20031118")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 10:35

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Set Items Description

S1 677582 S ISOLATION? OR STI? ? OR DIELECTRIC?(5N)(GROOVE? ? OR CHANNEL? ? OR TRENCH??? OR GAP? ? OR OPENING?)  
S2 26581846 S DETECT? OR SENSING OR SENSE OR SENSES OR DETECT? OR MEASUR? OR MONITOR? OR IDENTIF? OR DETERMIN?  
S3 854550 S GATE OR GATES OR GATELINE?  
S4 14717390 S POTENTIAL OR VOLTAGE OR ELECTRIC? OR CURRENT? OR EMF? ?  
S5 2655 S S1 AND (S2 OR TEST????) AND S3 AND S4  
S6 5521796 S SEMICONDUCTOR? OR SEMI()CONDUCTOR? OR SUBSTRATE? OR WAFER?  
S7 1635 S S5 AND S6  
S8 180 S S1 (6N) (S2 OR TEST????) (6N) S3 (6N) S4  
S9 106 S S8 AND S6  
S10 81 S S9 AND PY<=2003  
S11 56 RD (unique items)  
S12 7 S S11 AND PD<=20031118  
S13 57669 S (S2 OR TEST????)(3N)(VOID? OR S1)  
S14 48606 S (S2 OR TEST????)(2N)(VOID? OR S1)  
S15 2152 S S6 AND S14  
S16 848 S S15 AND (S3 OR S4)  
S17 383 S S6 (10N)S14  
S18 38 S S17(10N)(S3 OR S4)  
S19 33 RD (unique items)  
S20 33 S S19 NOT S12  
S21 28 S S20 AND PY<=2003  
S22 54 S S11 NOT S20  
S23 47 S S22 NOT S12

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